

## **Software License Agreement** **For SafeTI Hercules Diagnostic Library CSP (Production)**

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  - b. Governing Language. This Agreement is written and executed in the English language and shall be authoritative and controlling, whether or not translated into a language other than English to comply with law or for reference purposes. If a translation of this Agreement is required for any purpose, including but not limited to registration of the Agreement pursuant to any governmental laws, regulations or rules, you shall be solely responsible for creating such translation.
13. **Contingencies.** TI shall not be in breach of this Agreement and shall not be liable for any non-performance or delay in performance if such non-performance or delay is due to a force majeure event or other circumstances beyond TI’s reasonable control.
14. **Entire Agreement.** This is the entire agreement between you and TI and this Agreement supersedes any prior agreement between the parties related to the subject matter of this Agreement. Notwithstanding the foregoing, any signed and effective software license agreement relating to the subject matter hereof and stating expressly that such agreement shall control regardless of any subsequent click-wrap, shrink-wrap or web-wrap, shall supersede the terms of this Agreement. No amendment or modification of this Agreement will be effective unless in writing and signed by a duly authorized representative of TI. You hereby warrant and represent that you have obtained all authorizations and other applicable consents required empowering you to enter into this Agreement.

**Exhibit 1**  
**Licensed Materials and TI Devices**

1. TI device(s):  
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2. Licensed Materials

Licensed Software for use with TI Devices only	Format	ECCN
SafeTI Hercules Diagnostic Library and TPS65381 Driver	Source Code	EAR99
SafeTI Diagnostic Library Test Automation Unit	Executable Tool	EAR99
	Test Scripts Source	EAR99
	Test case xls	EAR99
LDRAunit-TI-Qual_C_CPP	Executable Tool	EAR99

Compliance Support Package Documentation	
Title	Description
<b>Requirements and Design</b>	
Software Safety Requirements specification	This document contains software safety requirements specification for the SafeTI Hercules Diagnostic Library.
Software Architecture Document	This document describes the software architecture of the SafeTI Hercules Diagnostic Library.
Design Document	This document describes the software design of the SafeTI Hercules Diagnostic Library.
<b>Test Documents</b>	
Detailed Static Analysis Report	This report provides summary of the Software quality metrics and the MISRA-C 2004 violations.
Detailed Dynamic Analysis Report	This report provides summary of the Structural Coverage metrics (Statement, Branch, MC/DC Coverage metrics).
Test Results Report	This report provides detailed information about the results of the formal testing.
Traceability Matrix Report	This report provides the traceability matrix between different phases of software development.